

RMA201 IN50-PB50 SOLDER PASTE

FEATURES

- 8 Hour Stencil Life
- Excellent Wetting
- Large Process Window
- Slump Resistance
- 6 Hour Tack Time
- Aqueous Clean with Saponifier

DESCRIPTION

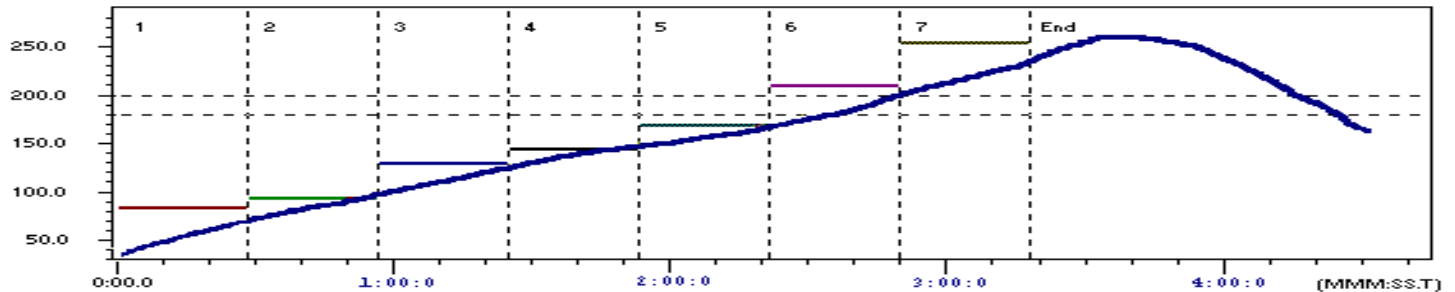
RMA201 is a mildly activated, pure gum rosin solder paste that is QQS571-E, QPL approved. The RMA201 formulation is designed specifically to allow reflow at higher than normal temperatures. Post-Process residues have undergone testing to insure high insulation resistance, and may be left on the PCB without degradation. Flux activity is adequate to wet most metal surfaces used on electronic circuit boards. RMA201 has a wide process window, and will accommodate a large variety of environments and process applications. This product performs well in continuous production, offering good slump resistance, high tack, and low post-process residues.

STANDARD PASTE COMPOSITION

Application Method	IPC Powder Size	Metal Load
Standard Stencil Printing	3	88.5%
Fine Pitch Stencil Printing	5	88%
Ultra-Fine Pitch Stencil Printing	5	87.5%
Dispensing Syringes	3	84%

Note: These are typical starting guidelines. To achieve optimal performance, actual metal load and particle size may vary per process, application, and environment.

REFLOW PROFILE



Rate of Rise 1-2°C / Sec Max	Pre-Heat Ramp to 150°C	Continue Through 150°C- 175°C	To Peak Temp 230°C ± 5°C	Time Above 210°C	Cooldown ≤ 4°C / SEC	Profile Length 3:00-3:45 Ambient to Peak
-	≤ 145 Sec	10-30 Sec	-	45-75 Sec	-	-

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PRINTER SETUP

Recommended Initial Printer Settings – Dependent on PCB and Pad Design	
Parameter	Recommended Initial Settings
Squeegee Pressure	1 – 1.5 lbs/inch of blade
Squeegee Speed	.5 – 6 inches/second
Snap-off Distance	On Contact 0.00 mm
PCB Separation Distance	0.030 - .050”
PCB Separation Speed	Medium

PASTE APPLICATION

Apply sufficient paste to the stencil to allow a smooth, even roll during the print cycle. A bead diameter of 1/2 to 5/8 inch is normally sufficient to begin. Apply small amounts of fresh solder paste to the stencil at frequent, controlled intervals to maintain paste chemistry and workable properties. Cleaning of your stencil will vary according to the application; however, it can be accomplished using AIM DJAW stencil cleaner. Use DJAW in moderation and remove any excess cleaner from stencil.

PLACEMENT INFORMATION

RMA201 provides the necessary tack time/force for today’s high-speed placement equipment. Ensuring proper support of PCBs during assembly and handling will enhance product performance and reliability.

HANDLING & STORAGE

- ▶ RMA201 In50-Pb50 has a 1 month shelf life when stored frozen at $\leq 0^{\circ}\text{C}$ ($\leq 32^{\circ}\text{F}$)
- ▶ Allow the solder paste to warm completely and naturally to ambient temperature (8 hours is recommended) prior to breaking seal for use
- ▶ Mix the product lightly and thoroughly for 1 to 3 minutes to ensure an even distribution of any separated material resulting from storage
- ▶ Do not store new and used paste in the same container. Re-seal any opened containers while not in use
- ▶ Replace the internal plug in conjunction with the cap of the 500 gram jar to ensure the best possible seal

CLEANING

RMA201 can be cleaned if necessary, with saponified tap water. We recommend AIMTERGE 520; however, deionized water is recommended for the final rinse. A temperature of 212°C - 302°C (100°F - 150°F) is sufficient for removing any residues. An in-line or other pressurized spray cleaning system is suggested, but is not required.

SAFETY

Use with adequate ventilation and proper personal protective equipment. Refer to the accompanying Safety Data Sheet for any specific emergency information. Do not dispose of any hazardous materials in non-approved containers.